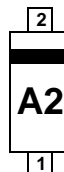


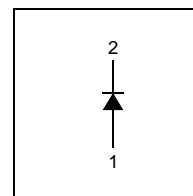
## BAT54HT1G



SOD-323



Connection Diagram



### Small Signal Diode

#### Absolute Maximum Ratings \* $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
$V_{RRM}$	Maximum Repetitive Reverse Voltage	30	V
$I_{F(AV)}$	Average Rectified Forward Current	200	mA
$I_{FSM}$	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second	600	mA
$T_{STG}$	Storage Temperature Range	-65 to +150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$

\* These ratings are limiting values above which the serviceability of the diode may be impaired.

**NOTES:**

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

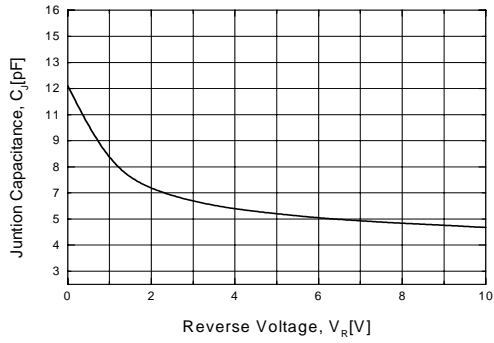
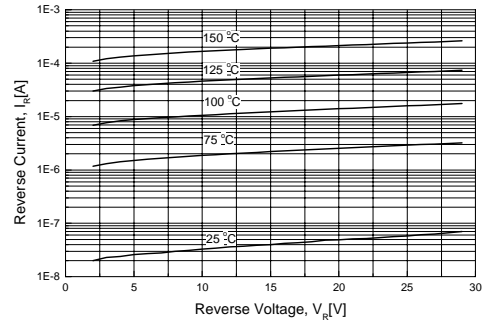
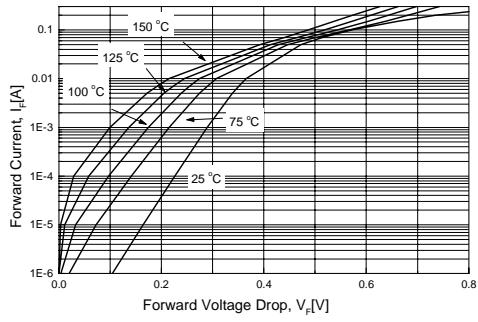
### Thermal Characteristics

Symbol	Parameter	Value	Units
$P_D$	Power Dissipation	200	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	600	$^\circ\text{C}/\text{W}$

### Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

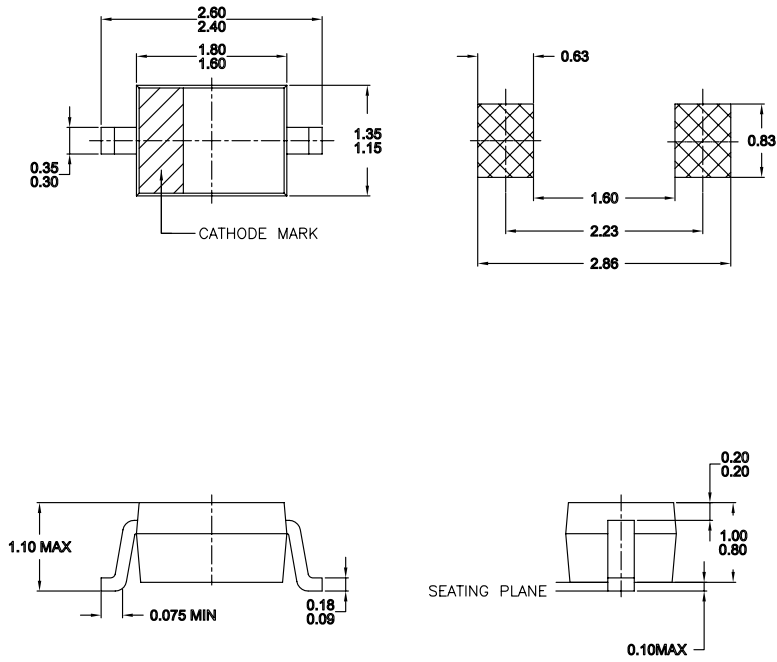
Symbol	Parameter	Test Conditions	Min.	Max.	Units
$V_R$	Breakdown Voltage	$I_R = 10\mu\text{A}$	30		V
$V_F$	Forward Voltage	$I_F = 0.1\text{mA}$ $I_F = 1.0\text{mA}$ $I_F = 10\text{mA}$ $I_F = 30\text{mA}$ $I_F = 100\text{mA}$		240 320 400 500 0.8	mV mV mV mV V
$I_R$	Reverse Leakage	$V_R = 25\text{V}$		2.0	$\mu\text{A}$
$C_T$	Total Capacitance	$V_R = 1\text{V}$ , $f = 1.0\text{MHz}$		10	pF
$t_{rr}$	Reverse Recovery Time	$I_F = I_R = 10\text{mA}$ , $I_{RR} = 1.0\text{mA}$ , $R_L = 100\Omega$		5.0	ns

# Typical Characteristics



Package Dimension

SOD-323



- NOTES: UNLESS OTHERWISE SPECIFIED  
 A) THIS PACKAGE CONFORMS TO EIAJ SC76  
 B) ALL DIMENSIONS ARE IN MILLIMETERS.  
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.  
 D) DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994

Dimensions in Millimeters

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## PRODUCT STATUS DEFINITIONS

### Definition of Terms

Datasheet Identification	Product Status	Definition
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